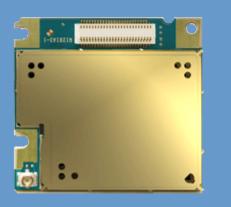


MC55i-W

Version: 01.301 Docld: MC55i-W_HIO_v01.301





MC55-W Hardware Interface Overview
01.301
2011-3-8
MC55i-W_HIO_v01.301
Confidential / Released
MC55i-W

GENERAL NOTE

THE USE OF THE PRODUCT INCLUDING THE SOFTWARE AND DOCUMENTATION (THE "PROD-UCT") IS SUBJECT TO THE RELEASE NOTE PROVIDED TOGETHER WITH PRODUCT. IN ANY EVENT THE PROVISIONS OF THE RELEASE NOTE SHALL PREVAIL. THIS DOCUMENT CON-TAINS INFORMATION ON CINTERION PRODUCTS. THE SPECIFICATIONS IN THIS DOCUMENT ARE SUBJECT TO CHANGE AT CINTERION'S DISCRETION. CINTERION WIRELESS MODULES GMBH GRANTS A NON-EXCLUSIVE RIGHT TO USE THE PRODUCT. THE RECIPIENT SHALL NOT TRANSFER, COPY, MODIFY, TRANSLATE, REVERSE ENGINEER, CREATE DERIVATIVE WORKS; DISASSEMBLE OR DECOMPILE THE PRODUCT OR OTHERWISE USE THE PRODUCT EXCEPT AS SPECIFICALLY AUTHORIZED. THE PRODUCT AND THIS DOCUMENT ARE PROVIDED ON AN "AS IS" BASIS ONLY AND MAY CONTAIN DEFICIENCIES OR INADEQUACIES. TO THE MAXIMUM EXTENT PERMITTED BY APPLICABLE LAW, CINTERION WIRELESS MODULES GMBH DIS-CLAIMS ALL WARRANTIES AND LIABILITIES. THE RECIPIENT UNDERTAKES FOR AN UNLIMITED PERIOD OF TIME TO OBSERVE SECRECY REGARDING ANY INFORMATION AND DATA PRO-VIDED TO HIM IN THE CONTEXT OF THE DELIVERY OF THE PRODUCT. THIS GENERAL NOTE SHALL BE GOVERNED AND CONSTRUED ACCORDING TO GERMAN LAW.

Copyright

Transmittal, reproduction, dissemination and/or editing of this document as well as utilization of its contents and communication thereof to others without express authorization are prohibited. Offenders will be held liable for payment of damages. All rights created by patent grant or registration of a utility model or design patent are reserved.

Copyright © 2011, Cinterion Wireless Modules GmbH

Trademark Notice

Microsoft and Windows are either registered trademarks or trademarks of Microsoft Corporation in the United States and/or other countries. All other registered trademarks or trademarks mentioned in this document are property of their respective owners.



Contents

1	Intro	duction	6
	1.1	Related documents	6
	1.2	Terms and Abbreviations	7
	1.3	Regulatory and Type Approval Information	10
		1.3.1 Directives and Standards	
		1.3.2 SAR Requirements Specific to Portable Mobiles	
		1.3.3 Safety Precautions	
2	Prod	luct Concept	15
	2.1	MC55i-W Key Features at a Glance	15
3	Appl	ication Interface	17
	3.1	Operating Modes	
4	Ante	nna Interface	
5	Elec	trical, Reliability and Radio Characteristics	
	5.1	Absolute Maximum Ratings	
	5.2	Operating Temperatures	
	5.3	Storage Conditions	
	5.4	Reliability Characteristics	
	5.5	Electrical Specifications of the Application Interface	
	5.6	Power Supply Ratings	
6	Mecl	nanics	
	6.1	Mechanical Dimensions of MC55i-W	
	6.2	Board-to-Board Connector	
		6.2.1 Mechanical Dimensions of the Hirose DF12 Connector	
7	Refe	rence Approval	
	7.1	Reference Equipment for Type Approval	
	7.2	Compliance with FCC Rules and Regulations	



Tables

Table 1:	Directives	10
Table 2:	Standards of North American type approval	10
Table 3:	Standards of European type approval	10
Table 4:	Requirements of quality	11
Table 5:	Standards of the Ministry of Information Industry of the	
	People's Republic of China	11
Table 6:	Toxic or hazardous substances or elements with defined concentration limits	12
Table 7:	Overview of operating modes	18
Table 8:	Return loss	19
Table 9:	Absolute maximum ratings	20
Table 10:	Board temperature	21
Table 11:	Ambient temperature according to IEC 60068-2 (w/o forced air circulation)	21
Table 12:	Ambient temperature with forced air circulation (air speed 0.9m/s)	21
Table 13:	Storage conditions	22
Table 14:	Summary of reliability test conditions	23
Table 15:	Power supply ratings	25
Table 16:	Ordering information DF12 series	27
Table 17:	Electrical and mechanical characteristics of the Hirose DF12C connector	27



Figures

Figure 1:	Pin assignment	24
	MC55i-W – top view	
	Hirose DF12C receptacle on MC55i-W	27
Figure 4:	Header Hirose DF12 series	27
Figure 5:	Mechanical dimensions of Hirose DF12 connector	28
Figure 6:	Reference equipment for approval	29



1 Introduction

This document¹ describes the hardware of the MC55i-W module that connects to the cellular device application and the air interface. It helps you quickly retrieve interface specifications, electrical and mechanical details and information on the requirements to be considered for integrating further components.

1.1 Related documents

- [1] MC55i-W AT Command Set
- [2] MC55i-W Release Notes

Prior to using the MC55i-W modules or upgrading to a new firmware release, please carefully read the latest product information.

For further information visit the Cinterion Wireless Modules Website: http://www.cinterion.com

^{1.} The document is effective only if listed in the appropriate Release Notes as part of the technical documentation delivered with your Cinterion Wireless Modules product.



1.2 Terms and Abbreviations

Abbreviation	Description
ADC	Analog-to-Digital Converter
AFC	Automatic Frequency Control
AGC	Automatic Gain Control
ANSI	American National Standards Institute
ARFCN	Absolute Radio Frequency Channel Number
ARP	Antenna Reference Point
ASC0 / ASC1	Asynchronous Serial Controller. Abbreviations used for first and second serial inter- face of MC55i-W
ASIC	Application Specific Integrated Circuit
В	Thermistor Constant
B2B	Board-to-board connector
BER	Bit Error Rate
BTS	Base Transceiver Station
CB or CBM	Cell Broadcast Message
CE	Conformité Européene (European Conformity)
CHAP	Challenge Handshake Authentication Protocol
CPU	Central Processing Unit
CS	Coding Scheme
CSD	Circuit Switched Data
CTS	Clear to Send
DAC	Digital-to-Analog Converter
DAI	Digital Audio Interface
dBm0	Digital level, 3.14dBm0 corresponds to full scale, see ITU G.711, A-law
DCE	Data Communication Equipment (typically modems, e.g. GSM module)
DCS 1800	Digital Cellular System, also referred to as PCN
DRX	Discontinuous Reception
DSB	Development Support Box
DSP	Digital Signal Processor
DSR	Data Set Ready
DTE	Data Terminal Equipment (typically computer, terminal, printer or, for example, GSM application)
DTR	Data Terminal Ready
DTX	Discontinuous Transmission
EFR	Enhanced Full Rate
EGSM	Enhanced GSM

MC55i-W Hardware Interface Overview

1.2 Terms and Abbreviations



Abbreviation	Description
EMC	Electromagnetic Compatibility
ESD	Electrostatic Discharge
ETS	European Telecommunication Standard
FCC	Federal Communications Commission (U.S.)
FDMA	Frequency Division Multiple Access
FR	Full Rate
GMSK	Gaussian Minimum Shift Keying
GPRS	General Packet Radio Service
GSM	Global Standard for Mobile Communications
HiZ	High Impedance
HR	Half Rate
I/O	Input/Output
IC	Integrated Circuit
IMEI	International Mobile Equipment Identity
ISO	International Standards Organization
ITU	International Telecommunications Union
kbps	kbits per second
LED	Light Emitting Diode
Li-Ion	Lithium-Ion
Mbps	Mbits per second
MMI	Man Machine Interface
MO	Mobile Originated
MS	Mobile Station (GSM module), also referred to as TE
MSISDN	Mobile Station International ISDN number
MT	Mobile Terminated
MTTF	Mean time to failure
NTC	Negative Temperature Coefficient
OEM	Original Equipment Manufacturer
PA	Power Amplifier
PAP	Password Authentication Protocol
PBCCH	Packet Switched Broadcast Control Channel
PCB	Printed Circuit Board
PCL	Power Control Level
PCM	Pulse Code Modulation
PCN	Personal Communications Network, also referred to as DCS 1800
PCS	Personal Communication System, also referred to as GSM 1900

1.2 Terms and Abbreviations



Abbreviation	Description
PDU	Protocol Data Unit
PLL	Phase Locked Loop
PPP	Point-to-point protocol
PSU	Power Supply Unit
R&TTE	Radio and Telecommunication Terminal Equipment
RAM	Random Access Memory
RF	Radio Frequency
RMS	Root Mean Square (value)
ROM	Read-only Memory
RTC	Real Time Clock
Rx	Receive Direction
SAR	Specific Absorption Rate
SELV	Safety Extra Low Voltage
SIM card	Subscriber Identification Module card; specifies a UICC with SIM application
SMS	Short Message Service
SRAM	Static Random Access Memory
ТА	Terminal adapter (e.g. GSM module)
TDMA	Time Division Multiple Access
TE	Terminal Equipment, also referred to as DTE
Тх	Transmit Direction
UART	Universal asynchronous receiver-transmitter
UICC	USIM Integrated Circuit Card
UMTS	Universal Mobile Telecommunications System
URC	Unsolicited Result Code
USIM	UMTS Subscriber Identification Module
USSD	Unstructured Supplementary Service Data
VSWR	Voltage Standing Wave Ratio
Phonebook abb	previations
FD	SIM fixdialing phonebook
LD	SIM last dialling phonebook (list of numbers most recently dialled)
MC	Mobile Equipment list of unanswered MT calls (missed calls)
ME	Mobile Equipment phonebook
ON	Own numbers (MSISDNs) stored on SIM or ME
RC	Mobile Equipment list of received calls
SM	SIM phonebook



1.3 **Regulatory and Type Approval Information**

1.3.1 **Directives and Standards**

MC55i-W has been designed to comply with the directives and standards listed below. It is the responsibility of the application manufacturer to ensure compliance of the final product with all provisions of the applicable directives and standards as well as with the technical specifications provided in the "MC55i-W Hardware Interface Description".²

Table 1: Directives

99/05/EC	Directive of the European Parliament and of the council of 9 March 1999 on radio equipment and telecommunications terminal equipment and the mutual recognition of their conformity (in short referred to as R&TTE Direc- tive 1999/5/EC). The product is labeled with the CE conformity mark C € 0682
2002/95/EC	Directive of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equip- ment (RoHS)

Table 2: Standards of North American type approval	
CFR Title 47	Code of Federal Regulations, Part 22 and Part 24 (Telecommunications, PCS); US Equipment Authorization FCC
UL 60 950	Product Safety Certification (Safety requirements)
NAPRD.03 V5.4	Overview of PCS Type certification review board Mobile Equipment Type Certification and IMEI control PCS Type Certification Review board (PTCRB)
RSS132 (Issue2) RSS133 (Issue5)	Canadian Standard

Table 3: Standards of European type approval

3GPP TS 51.010-1	Digital cellular telecommunications system (Phase 2); Mobile Station (MS) conformance specification
ETSI EN 301 511 V9.0.2	Candidate Harmonized European Standard (Telecommunications series) Global System for Mobile communications (GSM); Harmonized standard for mobile stations in the GSM 900 and DCS 1800 bands covering essen- tial requirements under article 3.2 of the R&TTE directive (1999/5/EC) (GSM 13.11 version 7.0.1 Release 1998)
GCF-CC V3.40	Global Certification Forum - Certification Criteria
ETSI EN 301 489-1 V1.8.1	Candidate Harmonized European Standard (Telecommunications series) Electro Magnetic Compatibility and Radio spectrum Matters (ERM); Elec- tro Magnetic Compatibility (EMC) standard for radio equipment and ser- vices; Part 1: Common Technical Requirements

² Manufacturers of applications which can be used in the US shall ensure that their applications have a PTCRB approval. For this purpose they can refer to the PTCRB approval of the respective module.

1.3 Regulatory and Type Approval Information

ETSI EN 301 489-7 V1.3.1	Candidate Harmonized European Standard (Telecommunications series) Electro Magnetic Compatibility and Radio spectrum Matters (ERM); Elec- tro Magnetic Compatibility (EMC) standard for radio equipment and ser- vices; Part 7: Specific conditions for mobile and portable radio and ancillary equipment of digital cellular radio telecommunications systems (GSM and DCS)
EN 60950-1:2006	Safety of information technology equipment

Table 3: Standards of European type approval

Table 4: Requirements of quality

IEC 60068	Environmental testing
DIN EN 60529	IP codes

Table 5:	Standards of the	Ministry of Info	rmation Industry	of the People's	Republic of China
Table 5.		winning of fine	initiation initiation y	of the Foople S	

SJ/T 11363-2006	"Requirements for Concentration Limits for Certain Hazardous Sub- stances in Electronic Information Products" (2006-06).	
SJ/T 11364-2006	"Marking for Control of Pollution Caused by Electronic Information Products" (2006-06).	
	According to the "Chinese Administration on the Control of Pollution caused by Electronic Information Products" (ACPEIP) the EPUP, i.e., Environmental Protection Use Period, of this product is 20 years as per the symbol shown here, unless otherwise marked. The EPUP is valid only as long as the product is operated within the operating limits described in the Cin- terion Wireless Modules Hardware Interface Description.	
	Please see Table 6 for an overview of toxic or hazardous substances or elements that might be contained in product parts in concentrations above the limits defined by SJ/T 11363-2006.	



1.3 Regulatory and Type Approval Information

部件名称	有毒有害物质或元素 Hazardous substances					
Name of the part	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
金属部件 (Metal Parts)	0	0	0	0	0	0
电路模块 (Circuit Modules)	х	0	0	0	0	0
电缆及电缆组件 (Cables and Cable Assemblies)	o	ο	0	o	o	0
塑料和聚合物部件 (Plastic and Polymeric parts)	o	о	0	о	o	0

Table 6: Toxic or hazardous substances or elements with defined concentration limits

0:

表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006 标准规定的限量要求以下。 Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X:

表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006标准规定的限量要求。 Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part *might exceed* the limit requirement in SJ/T11363-2006.



1.3.2 SAR Requirements Specific to Portable Mobiles

Mobile phones, PDAs or other portable transmitters and receivers incorporating a GSM module must be in accordance with the guidelines for human exposure to radio frequency energy. This requires the Specific Absorption Rate (SAR) of portable MC55i-W based applications to be evaluated and approved for compliance with national and/or international regulations.

Since the SAR value varies significantly with the individual product design manufacturers are advised to submit their product for approval if designed for portable use. For European and US markets the relevant directives are mentioned below. It is the responsibility of the manufacturer of the final product to verify whether or not further standards, recommendations or directives are in force outside these areas.

Products intended for sale on US markets

ES 59005/ANSI C95.1 Considerations for evaluation of human exposure to Electromagnetic Fields (EMFs) from Mobile Telecommunication Equipment (MTE) in the frequency range 30MHz - 6GHz

Products intended for sale on European markets

EN 50360: Product standard to demonstrate the compliance of mobile phones with the basic restrictions related to human exposure to electromagnetic fields (300MHz - 3GHz)



1.3.3 Safety Precautions

The following safety precautions must be observed during all phases of the operation, usage, service or repair of any cellular terminal or mobile incorporating MC55i-W. Manufacturers of the cellular terminal are advised to convey the following safety information to users and operating personnel and to incorporate these guidelines into all manuals supplied with the product. Failure to comply with these precautions violates safety standards of design, manufacture and intended use of the product. Cinterion Wireless Modules GmbH assumes no liability for customer failure to comply with these precautions.

	When in a hospital or other health care facility, observe the restrictions on the use of mobiles. Switch the cellular terminal or mobile off, if instructed to do so by the guide- lines posted in sensitive areas. Medical equipment may be sensitive to RF energy.
	The operation of cardiac pacemakers, other implanted medical equipment and hearing aids can be affected by interference from cellular terminals or mobiles placed close to the device. If in doubt about potential danger, contact the physician or the manufac- turer of the device to verify that the equipment is properly shielded. Pacemaker patients are advised to keep their hand-held mobile away from the pacemaker, while it is on.
X	Switch off the cellular terminal or mobile before boarding an aircraft. Make sure it can- not be switched on inadvertently. The operation of wireless appliances in an aircraft is forbidden to prevent interference with communications systems. Failure to observe these instructions may lead to the suspension or denial of cellular services to the offender, legal action, or both.
	Do not operate the cellular terminal or mobile in the presence of flammable gases or fumes. Switch off the cellular terminal when you are near petrol stations, fuel depots, chemical plants or where blasting operations are in progress. Operation of any electri- cal equipment in potentially explosive atmospheres can constitute a safety hazard.
	Your cellular terminal or mobile receives and transmits radio frequency energy while switched on. Remember that interference can occur if it is used close to TV sets, radios, computers or inadequately shielded equipment. Follow any special regulations and always switch off the cellular terminal or mobile wherever forbidden, or when you suspect that it may cause interference or danger.
a	Road safety comes first! Do not use a hand-held cellular terminal or mobile when driv- ing a vehicle, unless it is securely mounted in a holder for handsfree operation. Before making a call with a hand-held terminal or mobile, park the vehicle.
	Handsfree devices must be installed by qualified personnel. Faulty installation or oper- ation can constitute a safety hazard.
sos	IMPORTANT! Cellular terminals or mobiles operate using radio signals and cellular networks. Because of this, connection cannot be guaranteed at all times under all conditions. Therefore, you should never rely solely upon any wireless device for essential commu- nications, for example emergency calls. Remember, in order to make or receive calls, the cellular terminal or mobile must be switched on and in a service area with adequate cellular signal strength. Some networks do not allow for emergency calls if certain network services or phone features are in use (e.g. lock functions, fixed dialling etc.). You may need to deactivate those features before you can make an emergency call. Some networks require that a valid SIM card be properly inserted in the cellular termi- nal or mobile.



2 Product Concept

2.1 MC55i-W Key Features at a Glance

Feature	Implementation
General	
Frequency bands	Quad band: GSM 850/900/1800/1900MHz
GSM class	Small MS
Output power (according to Release 99, V5)	Class 4 (+33dBm ±2dB) for EGSM850 Class 4 (+33dBm ±2dB) for EGSM900 Class 1 (+30dBm ±2dB) for GSM1800 Class 1 (+30dBm ±2dB) for GSM1900
Power supply	$3.3V \le V_{BATT+} \le 4.8V$
Operating temperature (board temperature)	Normal operation: -30°C to +85°C Restricted operation: -40°C to -30°C and +85°C to +90°C
Physical	Dimensions: 32.5mm x 35mm x max. 3.1mm Weight: approx. 6g
RoHS	All hardware components fully compliant with EU RoHS Directive
GSM / GPRS features	
Data transfer	 GPRS: Multislot Class 10 Full PBCCH support Mobile Station Class B Coding Scheme 1 – 4 CSD: V.110, RLP, non-transparent 2.4, 4.8, 9.6, 14.4kbps USSD PPP-stack for GPRS data transfer
SMS	Point-to-point MT and MO Cell broadcast Text and PDU mode Storage: SIM card plus 25 SMS locations in mobile equipment Transmission of SMS alternatively over CSD or GPRS. Preferred mode can be user defined.
Fax	Group 3; Class 2
Audio	 Speech codecs: Half Rate (ETS 06.20) Full Rate (ETS 06.10) Enhanced Full Rate (ETS 06.50 / 06.60 / 06.80) Adaptive Multi Rate AMR Handsfree operation, echo cancellation, noise reduction, 7 different ringing tones / melodies

MC55i-W Hardware Interface Overview

2.1 MC55i-W Key Features at a Glance



Feature	Implementation
Software	
AT commands	Hayes 3GPP TS 27.007, TS 27.005, Cinterion Wireless Modules AT commands for RIL compatibility
SIM Application Toolkit	Supports SAT class 3, GSM 11.14 Release 99, support of letter class "c"
TCP/IP stack	Protocols: TCP, UDP, HTTP, FTP, SMTP, POP3 Access by AT commands
Firmware update	Windows executable for update over serial interface ASC0
Interfaces	
2 serial interfaces	 ASC0: 8-wire modem interface with status and control lines, unbalanced, asynchronous Fixed bit rates: 300bps to 230,000bps Autobauding: 1,200bps to 230,000bps Supports RTS0/CTS0 hardware handshake and software XON/XOFF flow control. Multiplex ability according to GSM 07.10 Multiplexer Protocol. ASC1: 4-wire, unbalanced asynchronous interface Fixed bit rates: 300bps to 230,000bps
Audio	1 analog interface 1 digital interface (PCM)
SIM interface	Supported SIM cards: 3V, 1.8V External SIM card reader has to be connected via interface connector (note that card reader is not part of MC55i-W)
Antenna	$50\Omega.$ External antenna can be connected via antenna connector or solderable pad.
Module interface	50-pin board-to-board connector
Power on/off, Reset	
Power on/off	Switch-on by hardware pin IGT Switch-off by AT command (AT^SMSO) Automatic switch-off in case of critical temperature and voltage conditions
Reset	Orderly shutdown and reset by AT command
Special features	
Real time clock	Timer functions via AT commands
Phonebook	SIM and phone
TTY/CTM support	Integrated CTM modem
Evaluation kit	
DSB75	DSB75 Evaluation board designed to test and type approve Cinterion Wire- less Module and provide a sample configuration for application engineer- ing. A special adapter is required to connect the module to the DSB75.



3 Application Interface

MC55i-W is equipped with a 50-pin board-to-board connector that connects to the external application. The host interface incorporates several sub-interfaces: power supply, SIM interface, serial interface ASC0, serial interface ASC1, analog audio interface, and DAI/PCM interface (for details see Chapter 2 and Section 5.5).



3.1 Operating Modes

The table below briefly summarizes the various operating modes referred to in the following sections.

 Table 7:
 Overview of operating modes

Mode	Function			
Normal operation	GSM / GPRS SLEEP	Various powersave modes set with AT+CFUN command. Software is active to minimum extent. If the module was reg- istered to the GSM network in IDLE mode, it is registered and paging with the BTS in SLEEP mode, too. Power saving can be chosen at different levels: The NON-CYCLIC SLEEP mode (AT+CFUN=0) disables the AT interface. The CYCLIC SLEEP modes AT+CFUN= 7 and 9 alternatingly activate and deacti- vate the AT interfaces to allow permanent access to all AT commands.		
	GSM IDLE	Software is active. Once registered to the GSM network, pag- ing with BTS is carried out. The module is ready to send and receive.		
	GSM TALK	Connection between two subscribers is in progress. Power consumption depends on network coverage individual settings, such as DTX off/on, FR/EFR/HR, hopping sequences, antenna.		
	GPRS IDLE	Module is ready for GPRS data transfer, but no data is cur- rently sent or received. Power consumption depends on net- work settings and GPRS configuration (e.g. multislot settings).		
	GPRS DATA	GPRS data transfer in progress. Power consumption depends on network settings (e.g. power control level), uplink / down- link data rates and GPRS configuration (e.g. used multislot settings).		
Power Down	Normal shutdown after sending the AT^SMSO command. Only a voltage regulate is active for powering the RTC. Software is not active. Interfaces are not access ble. Operating voltage (connected to BATT+) remains applied.			
Alarm mode	Restricted operation launched by RTC alert function while the module is in Power Down mode. Module will not be registered to GSM network. Limited number of AT commands is accessible.			

4 Antenna Interface

The RF interface has an impedance of 50Ω . MC55i-W is capable of sustaining a total mismatch at the antenna connector or pad without any damage, even when transmitting at maximum RF power.

The external antenna must be matched properly to achieve best performance regarding radiated power, DC-power consumption and harmonic suppression. Matching networks are not included on the MC55i-W PCB and should be placed in the host application.

Regarding the return loss MC55i-W provides the following values:

Table 8: Return loss

State of module	Return loss of module	Recommended return loss of application
Receive	<u>≥</u> 8dB	≥ 12dB
Transmit	not applicable	≥ 12dB
Idle	≤ 5dB	not applicable

The connection of the antenna or other equipment must be decoupled from DC voltage. This is necessary because the antenna connector is DC coupled to ground via an inductor for ESD protection.



5 Electrical, Reliability and Radio Characteristics

5.1 Absolute Maximum Ratings

Absolute maximum ratings for supply voltage and voltages on digital and analog pins of MC55i-W are listed in Table 9. Exceeding these values will cause permanent damage to MC55i-W.

Table 9:	Absolute	maximum	ratings
Table 5.	7.0501010	maximum	raungo

Parameter	Min	Мах	Unit
Supply voltage BATT+	-0.3	+6.0	V
Voltage at digital pins in normal operation	-0.3	+3.3	V
Voltage at all digital pins in Power Down mode	-0.3	+0.3	V
Voltage at SIM interface, CCVCC 1.8V in normal Operation	-0.3	+2.2	V
Voltage at SIM interface, CCVCC 2.85V in normal Operation	-0.3	+3.3	V
Voltage at analogue pins in normal operation	-0.3	+3.0	V
Voltage at analogue pins in Power Down mode	-0.3	+0.3	V
VDDLP	-0.3	+2.5	V

5.2 **Operating Temperatures**

Please note that the module's lifetime, i.e., the MTTF (mean time to failure) may be reduced, if operated outside the restriced temperature range. A special URC reports whether the module enters or leaves the restriced temperature range (see [1]; AT^SCTM).

 Table 10:
 Board temperature

Parameter	Min	Тур	Max	Unit
Normal operation	-30	+25	+85	°C
Restricted operation	-40 to -30		+85 to +90	°C
Automatic shutdown ¹ Temperature measured on MC55i-W board	<-40		>+90	°C

^{1.} Due to temperature measurement uncertainty, a tolerance of $\pm 3^{\circ}$ C on the thresholds may occur.

Table 11:	Ambient temperature	according to IEC 6006	68-2 (w/o forced air circulation)
-----------	---------------------	-----------------------	-----------------------------------

Parameter	Min	Тур	Max	Unit
GSM Call @ max. RF-Power	-40		+75	°C
GPRS Class 8 @ max. RF-Power	-40		+75	°C
GPRS Class 10 @ max. RF-Power (quad band only)	-40		+60	°C

Table 12: Ambient temperature with forced air circulation (air speed 0.9m/s)

Parameter	Min	Тур	Max	Unit
GSM Call @ max. RF-Power	-40		+80	°C
GPRS Class 8 @ max. RF-Power	-40		+80	°C
GPRS Class 10 @ max. RF-Power (quad band only)	-40		+70	°C

Note that within the specified operating temperature ranges the board temperature may vary to a great extent depending on operating mode, used frequency band, radio output power and current supply voltage.

When data are transmitted over GPRS the quad band module variant automatically reverts to a lower Multislot Class if the temperature rises to the limit specified for normal operation and, vice versa, returns to the higher Multislot Class if the temperature is back to normal.



5.3 Storage Conditions

The conditions stated below are only valid for modules in their original packed state in weather protected, non-temperature-controlled storage locations. Normal storage time under these conditions is 12 months maximum.

Table 13:	Storage conditions
-----------	--------------------

Туре	Condition	Unit	Reference
Air temperature: Low High	-40 +85	°C	ETS 300 019-2-1: T1.2, IEC 60068-2-1 Ab ETS 300 019-2-1: T1.2, IEC 60068-2-2 Bb
Humidity relative: Low High Condens.	10 90 at 30°C 90-100 at 30°C	%	 ETS 300 019-2-1: T1.2, IEC 60068-2-56 Cb ETS 300 019-2-1: T1.2, IEC 60068-2-30 Db
Air pressure: Low High	70 106	kPa	IEC TR 60271-3-1: 1K4 IEC TR 60271-3-1: 1K4
Movement of surrounding air	1.0	m/s	IEC TR 60271-3-1: 1K4
Water: rain, dripping, icing and frosting	Not allowed		
Radiation: Solar Heat	1120 600	W/m ²	ETS 300 019-2-1: T1.2, IEC 60068-2-2 Bb ETS 300 019-2-1: T1.2, IEC 60068-2-2 Bb
Chemically active substances	Not recom- mended		IEC TR 60271-3-1: 1C1L
Mechanically active substances	Not recom- mended		IEC TR 60271-3-1: 1S1
Vibration sinusoidal: Displacement Acceleration Frequency range	1.5 5 2-9 9-200	mm m/s ² Hz	IEC TR 60271-3-1: 1M2
Shocks: Shock spectrum Duration Acceleration	semi-sinusoidal 1 50	ms m/s²	IEC 60068-2-27 Ea

5.4 Reliability Characteristics

The test conditions stated below are an extract of the complete test specifications.

Type of test	Conditions	Standard
Vibration	Frequency range: 10-20 Hz; acceleration: 3.1mm amplitude Frequency range: 20-500 Hz; acceleration: 5g Duration: 2h per axis = 10 cycles; 3 axes	DIN IEC 60068-2-6
Shock half-sinus	Acceleration: 500g Shock duration: 1msec 1 shock per axis 6 positions (± x, y and z)	DIN IEC 60068-2-27
Dry heat	Temperature: +70 ±2°C Test duration: 16 h Humidity in the test chamber: < 50%	EN 60068-2-2 Bb ETS 300019-2-7
Temperature change (shock)	Low temperature: -40°C ±2°C High temperature: +85°C ±2°C Changeover time: < 30s (dual chamber system) Test duration: 1 h Number of repetitions: 100	DIN IEC 60068-2-14 Na ETS 300019-2-7
Damp heat cyclic	High temperature: +55°C ±2°C Low temperature: +25°C ±2°C Humidity: 93% ±3% Number of repetitions: 6 Test duration: 12h + 12h	DIN IEC 60068-2-30 Db ETS 300019-2-5
Cold (constant exposure)	Temperature: -40 ±2°C Test duration: 16 h	DIN IEC 60068-2-1

Table 14: Summary of reliability test conditions



5.5 Electrical Specifications of the Application Interface

The Hirose DF12C board-to-board connector on MC55i-W is a 50-pin double-row receptacle. The names and the positions of the pins can be seen from Figure 2 which shows the top view of MC55i-W.

1	CCCLK	Not connected	50
2	CCVCC	Not connected	49
3	CCIO	EPP	48
4	CCRST	EPN	47
5	CCIN	VMICN	46
6	CCGND	VMICP	45
7	RXDDAI	MICP	44
8	TFSDAI	MICN	43
9	SCLK	AGND	42
10	TXDDAI	IGT	41
11	RFSDAI	EMERG_RST	40
12	Do not use	DCD0	39
13	STATUS	CTS1	38
14	RXD1	CTS0	37
15	RXD0	RTS1	36
16	TXD1	DTR0	35
17	TXD0	RTS0	34
18	VDDLP	DSR0	33
19	Not connected	RING0	32
20	Not connected	VDD	31
21	GND	BATT+	30
22	GND	BATT+	29
23	GND	BATT+	28
24	GND	BATT+	27
25	GND	BATT+	26

Figure 1: Pin assignment



5.6 **Power Supply Ratings**

Table 15: Power supply ratings

	Description	Conditions	Min	Тур	Max	Unit
BATT+ Supp	Supply voltage	Directly measured at module. Voltage must stay within the min/ max values, including voltage drop, ripple and spikes.	3.3	4.0	4.8	V
	Maximum allowed voltage drop during transmit burst	Normal condition, power control level for P _{out max}			400	mV
	Voltage ripple	Normal condition, power control level for P _{out max} @ f<250kHz @ f>250kHz			105 30	mV _{pp}
I _{VDDLP}	OFF state supply current	RTC backup @ BATT+ = 0V		6.0		μA
I _{BATT+} 1	OFF state supply current	POWER DOWN mode		45		μA
	Average supply	SLEEP mode ² @ DRX = 9		1.3		mA
	current	SLEEP mode ² @ DRX = 5		1.6		mA
		SLEEP mode ² @ DRX = 2		2.2		mA
		IDLE mode ² @ DRX = 2		9.5		mA
	Voice call GSM850/900, PCL=5		180		mA	
		GPRS data transfer GSM850/900 PCL=5, (1Tx/ 4Rx)		170		mA
		GPRS data transfer GSM850/900 PCL=5, (2Tx/ 3Rx)		310		mA
		Voice call GSM1800/1900, PCL=0		135		mA
		GPRS data transfer GSM1800/1900 PCL=0, (1Tx/ 4Rx)		130		mA
		GPRS data transfer GSM1800/1900 PCL=0, (2Tx/ 3Rx)		230		mA
		Voice call GSM850, PCL=5		1.35	1.38 ³	А
	Peak current during	Voice call GSM900, PCL=5		1.30	1.35 ³	А
GSM transmission burst	Voice call GSM1800, PCL=0		0.95	0.98 ³	A	
		Voice call GSM1900, PCL=0		0.89	0.92 ³	А

 $^{\rm 1.}$ With an impedance of $\rm Z_{\rm LOAD}{=}50\rm Ohm$ at the antenna connector.

^{2.} ASC0, ASC1 inactive

Measurements start 6 minutes after switching on the module,

Averaging times: SLEEP mode - 3 minutes; transfer modes - 1.5 minutes,

Communication tester settings: no neighbour cells, no cell reselection etc.,

RMC (Reference Measurement Channel)

^{3.} At total mismatch.



6 Mechanics

The following sections describe the mechanical dimensions of MC55i-W and give recommendations for integrating MC55i-W into the host application.

6.1 Mechanical Dimensions of MC55i-W

Figure 2 shows the top view on MC55i-W and provides an overview of the mechanical dimensions of the board.

Length: 35mm

Width: 32.5mm

Height: 3.1mm (including board-to-board connector), 2.9mm (excluding connector)

Weight: 6g

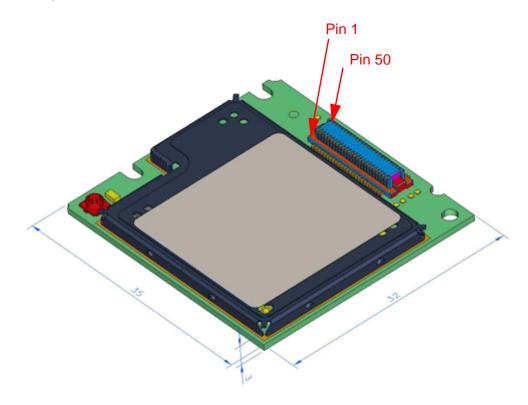


Figure 2: MC55i-W - top view



6.2 Board-to-Board Connector

This section provides specifications for the 50-pin board-to-board connector which serves as physical interface to the host application. The receptacle assembled on the MC55i-W PCB is type Hirose DF12C. Mating headers from Hirose are available in different stacking heights.



Figure 3: Hirose DF12C receptacle on MC55i-W





Figure 4: Header Hirose DF12 series

Item	Part number	Stacking height (mm)	HRS number
Receptacle on MC55i-W	DF12C(3.0)-50DS-0.5V(81)	3 - 5	537-0694-9-81
Headers DF12 series	DF12E(3.0)-50DP-0.5V(81) DF12E(3.5)-50DP-0.5V(81) DF12E(4.0)-50DP-0.5V(81) DF12E(5.0)-50DP-0.5V(81)	3.0 3.5 4.0 5.0	537-0834-6-** 537-0534-2-** 537-0559-3-** 537-0584-0-**

Note: The headers listed above are without boss and metal fitting. Please contact Hirose for details on other types of mating headers. Asterixed HRS numbers denote different types of packaging.

Parameter	Specification (50 pin board-to-board connector)
Number of contacts	50
Quantity delivered	2000 connectors per tape & reel
Voltage	50V
Rated current	0.3A max per contact
Resistance	0.05 Ω per contact
Dielectric withstanding voltage	500V RMS min
Operating temperature	-45°C+125°C
Contact material	phosphor bronze (surface: gold plated)
Insulator material	PA, beige natural
Stacking height	3.0 mm ; 3.5 mm ; 4.0 mm ; 5.0 mm
Insertion force	21.8N
Withdrawal force 1 st	10N
Withdrawal force 50 th	10N
Maximum connection cycles	50



6.2.1 Mechanical Dimensions of the Hirose DF12 Connector

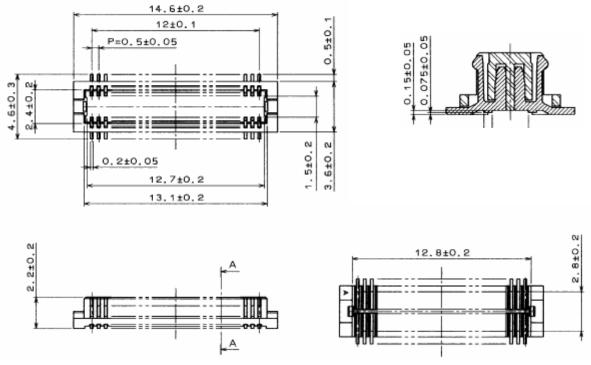


Figure 5: Mechanical dimensions of Hirose DF12 connector



7 Reference Approval

7.1 Reference Equipment for Type Approval

The Cinterion Wireless Modules reference setup submitted to type approve MC55i-W consists of the following components:

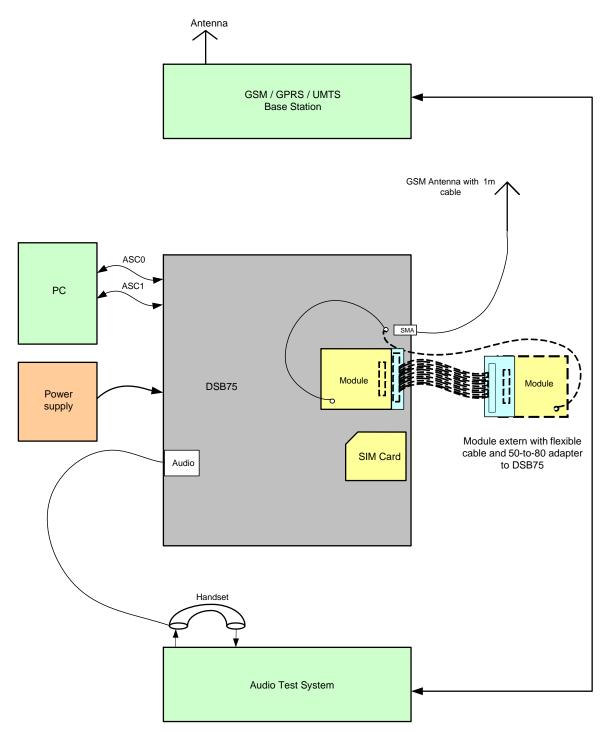


Figure 6: Reference equipment for approval



7.2 Compliance with FCC Rules and Regulations

The Equipment Authorization Certification for the Cinterion Wireless Modules reference application described in Section 7.1 will be registered under the following identifiers:

> FCC Identifier: QIPMC55I-W Industry Canada Certification Number: 7830A-MC55IW Granted to Cinterion Wireless Modules GmbH

Manufacturers of mobile or fixed devices incorporating MC55i-W modules are authorized to use the FCC Grants and Industry Canada Certificates of the MC55i-W modules for their own final products according to the conditions referenced in these documents. In this case, the FCC label of the module shall be visible from the outside, or the host device shall bear a second label stating "Contains FCC ID QIP*MC55I-W*", and accordingly "Contains IC 7830A-MC55IW".

IMPORTANT:

Manufacturers of portable applications incorporating MC55i-W modules are required to have their final product certified and apply for their own FCC Grant and Industry Canada Certificate related to the specific portable mobile. This is mandatory to meet the SAR requirements for portable mobiles (see Section 1.3.2 for detail).

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.